



Material Content Data Sheet



Sales Product Name				BTS50080-1TEB		Issued		1. August 2018	
MA#				MA002337754					
Package				PG-TO252-5-11		Weight*		357.41 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip_1	inorganic material	silicon	7440-21-3	4.425	1.24	1.24	12382	12382	
chip_2	inorganic material	silicon	7440-21-3	1.157	0.32	0.32	3238	3238	
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		172		
	non noble metal	iron	7439-89-6	0.205	0.06		572		
wire	non noble metal	copper	7440-50-8	204.243	57.14	57.22	571452	572196	
	non noble metal	aluminium	7429-90-5	2.028	0.57	0.57	5673	5673	
encapsulation	organic material	carbon black	1333-86-4	1.365	0.38		3820		
	plastics	epoxy resin	-	23.894	6.69		66854		
leadfinish	inorganic material	silicondioxide	60676-86-0	111.280	31.14	38.21	311350	382024	
	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14192	14192	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	213	214	
solder	non noble metal	tin	7440-31-5	0.069	0.02		194		
	noble metal	silver	7440-22-4	0.087	0.02		242		
glue	non noble metal	lead	7439-92-1	3.305	0.92	0.96	9246	9682	
	plastics	Polyimide	26023-21-2	0.143	0.04	0.04	399	399	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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